

Title (en)

Planer trimming resistor, its application and manufacturing process

Title (de)

Planarer Abgleichwiderstand, Anwendungen und Verfahren zu seiner Herstellung

Title (fr)

Élément résistif ajustable, son application et procédé de fabrication

Publication

EP 1093132 A3 20040602 (DE)

Application

EP 00115803 A 20000722

Priority

DE 19949607 A 19991015

Abstract (en)

[origin: EP1093132A2] The device has a substrate (1), a resistive layer (3) and a contact layer (6) on the resistive layer and with higher conductivity than and in contact with it at least at individual points (4). Material can be removed locally (7) above the resistive layer. The contact layer does not extend beyond the edges of the resistive layer. The resistive and contact layers can be strip-shaped with connection contacts at opposite ends of the contact layer. Independent claims are also included for the following: 1. a resistive bridge circuit; 2. a sensor with a deformable substrate and at least one resistance element; and 3. a method of manufacturing a balancing resistance.

IPC 1-7

H01C 17/24

IPC 8 full level

H01C 7/22 (2006.01)

CPC (source: EP US)

H01C 7/22 (2013.01 - EP US)

Citation (search report)

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- [YA] EP 0325234 A2 19890726 - TOSHIBA KK [JP]
- [YA] DE 2039920 A1 19720217 - SIEMENS AG
- [YA] DE 3919059 A1 19910103 - BOSCH GMBH ROBERT [DE]
- [A] PATENT ABSTRACTS OF JAPAN vol. 018, no. 324 (E - 1564) 20 June 1994 (1994-06-20)

Cited by

WO2007034463A1; US7598841B2; US7719403B2

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